AMENDMENTS TO THE CLAIMS:

Amend the claims as follows:

1. (Original) A solar cell having a silver paste electrode which has been dip-coated with lead-free solder, wherein said silver paste electrode is formed by firing silver paste, and powdery glass included in said silver paste has an average grain size of 11 μm at most.

2. (Withdrawn - Currently Amended) A solar cell having a silver paste electrode which has been dip-coated with lead-free solder, wherein said silver paste electrode is formed by firing silver paste, and an amount of powdery glass included in said silver paste is 2.8 to 10.0 mass %.

3. (Withdrawn – Currently Amended) A solar cell having a silver paste electrode which has been dip-coated with lead-free solder, wherein said silver paste electrode after firing has an average thickness of at least 15 μm.

4. (Withdrawn – Currently Amended) A fabrication method of a solar cell of claim 1 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein powdery glass sifted though a sieve having an opening diameter of 73 μm at most is used as said powdery glass included in said silver paste.

5. (Withdrawn – Currently Amended) A fabrication method of a solar cell of claim 1 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type

silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste at least two times.

6. (Withdrawn – Currently Amended) A fabrication method of a solar cell of claim 1 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

Claim 7. (Canceled)

8. (Currently Amended) A solar cell string interconnecting a solar cell having a silver paste electrode which has been dip-coated with lead-free solder and contains [[with]] an interconnector for a solar cell, wherein said paste electrode is formed by firing silver paste, and powdery glass included in said silver paste has an average grain size of 11 μm at most.

9. (Currently Amended) A solar cell module incorporated with a string interconnecting a solar cell having a silver paste electrode which has been dip-coated with lead-free solder with an interconnector for a solar cell, wherein said paste electrode is formed by firing silver paste, and powdery glass included in said silver paste has an average grain size of 11 μm at most .

10. (Withdrawn – Currently Amended) A solar cell module incorporated with a string interconnecting a solar cell having a silver paste electrode which has been dip-

coated with lead-free solder with an interconnector for a solar cell, wherein said paste electrode is formed by firing silver paste, and an amount of powdery glass included in said silver paste is 2.8 to 10.0 mass %.

11. (Withdrawn – Currently Amended) A solar cell module incorporated with a string interconnecting a solar cell having a silver paste electrode which has been dip-coated with lead-free solder with an interconnector for a solar cell, wherein said silver paste electrode after firing has an average thickness of at least 15 μm.

12. (new) The solar cell of claim 1 wherein the silver paste contains an amount of powdery glass in the range of 2.8 to 10.0 mass %.

13. (new) The solar cell of claim 1, wherein said silver paste electrode after firing has an average thickness of at least 15 μm.

14. (new) A fabrication method of a solar cell of claim 1 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

15. (new) A fabrication method of a solar cell of claim 12 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

16. (new) A fabrication method of a solar cell of claim 13 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

17. (new) The solar cell of claim 9, wherein said silver paste has an amount of powdery glass in the range of 2.8 to 10.0 mass %.

18. (new) The solar cell of claim 9, wherein said silver paste electrode after firing has an average thickness of at least 15 μm.

19. (new) A fabrication method of a solar cell of claim 2 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein powdery glass sifted though a sieve having an opening diameter of 73 μm at most is used as said powdery glass included in said silver paste.

20. (new) A fabrication method of a solar cell of claim 3 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein powdery glass sifted though a sieve having an opening diameter of 73 μm at most is used as said powdery glass included in said silver paste.

21. (new) A fabrication method of a solar cell of claim 2 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste at least two times.

22. (new) A fabrication method of a solar cell of claim 3 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste at least two times.

23. (new) A fabrication method of a solar cell of claim 2 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.

24. (new) A fabrication method of a solar cell of claim 3 comprising the steps of printing the silver paste at a partial region at a light receiving side of an anti-reflection film and at a partial region at a back side of a p type silicon substrate, firing said silver paste to form a silver paste electrode, and dip-coating said silver paste electrode with

lead-free solder, wherein the step of printing silver paste includes applying silver paste using a mask having a thickness of three times a wire diameter.